

**Amendments to the Claims**

1. *(Currently Amended)* An electronic device whose component body contains at least one stress relief element (4), a substrate (1) with an upper surface and side walls, at least one circuit element (2) located on said substrate (1) and at least one passivation and/or isolating layer (3) placed on said substrate (1), whereby said isolating layer (3) covers said at least one circuit element (2) and/or said substrate (1) and contains a top surface, at least one outer side surface which is located towards a side wall of said substrate and at least one outer edge, which is formed by said top surface and said at least one outer side surface, characterized in that the at least one stress relief element (4) is made out of a ductile material and simultaneously covers the top surface of said passivation and/or isolating layer (3) and overlaps said outer edge of said passivation and/or isolating layer (3) and extends along said outer side surface of said passivation and/or isolating layer (3) and d1) contacts the upper surface of the substrate (1) or d2) forms a bridge with at least one circuit element (2) in that way that the stress relief element is linked with the upper surface of the substrate (1) via at least one circuit element (2)

2. *(Currently Amended)* An electronic device according to claim 1, whereby said at least one stress relief element (4) is formed as a sealing ring, preferably in that way that it extends itself along at least two, preferably three or four side walls of the substrate, thus forming a ring-like structure.

3. *(Currently Amended)* An electronic device according to ~~claim 1~~ or claim 1, whereby said bridge formed by said stress relief element (4) and at least one circuit member (2) extends itself along said outer side surface of said passivation and/or isolating layer (3)

4. *(Currently Amended)* An electronic device according to ~~any one of claims 1 to 3~~ claim 1, whereby said stress relief element (4) covers the top surface of said passivation and/or isolating layer (3) and/or overlaps said outer edge of said passivation and/or isolating layer (3) and/or extends along said outer side surface of said passivation and/or isolating layer (3) in an amount of  $\geq 70\%$ , preferably  $\geq 80\%$  and  $\leq 90\%$ .

5. *(Currently Amended)* An electronic device according to ~~any one of claims 1 to 4~~ claim 1, whereby said passivation and/or isolating layer (3) is the passivation and/or isolating layer (3) which is located closest to at least one side wall of said substrate (1).

6. *(Currently Amended)* An electronic device according to ~~any one of claims 1 to 4~~ claim 1, furthermore having at least one stress relief element (4A) locally and/or electrically isolated from said first stress relief element (4).

7. . (*Currently Amended*) An electronic device according to ~~any one of claims 1 to 4~~claim 1, whereby the material of said stress relief element ~~(4)~~ is selected out of a group consisting essentially of aluminium, aluminium alloys, preferably with Si and/or Cu, Copper, Lead, Silver, Gold or mixtures thereof.

8. . (*Currently Amended*) An electronic device according to ~~any one of claims 1 to 6~~claim 1, whereby the tensile strength of said passivation and/or isolating layer ~~(3)~~ is higher than the tensile strength of said stress relief element ~~(4)~~.

9. . (*Currently Amended*) An electronic device according to ~~any one of claim 8~~claim 1, whereby the tensile strength of said passivation and/or isolating layer ~~(3)~~ is  $\geq 1 \times 10^8$  and  $\leq 1 \times 10^9$  Pa .

10. . (*Currently Amended*) An electronic device according to ~~any one of claim 8~~claim 1, whereby the tensile strength of said stress relief element ~~(4)~~ is  $\geq 1 \times 10^7$  and  $\leq 1 \times 10^8$  Pa.